

Sub
C2
B1
Cont

wherein the base substrate includes:

a first region in which a predetermined interconnect pattern has been formed and which will form a unit when separated from the base substrate; and

a second region positioned next to the first region in the longitudinal direction of the base substrate; and

wherein the second region has low-bending-resistance portions which are formed in regions that exclude and sandwich a central portion of the second region in the widthwise direction of the base substrate, for ensuring that the second region bends more readily in the direction in which the longitudinal axis of the base substrate bends, in comparison with the first region.

2. (Amended) The flexible interconnect substrate as defined in claim 1, wherein each of the low-bending-resistance portions is one of through-holes, cuts, and a thinner portion.

3. (Amended) The flexible interconnect substrate as defined in claim 1, wherein a high-bending-resistance portion is formed in each of the first region and the central portion of the second region in the widthwise direction of the base substrate;

wherein the high-bending-resistance portion is formed to avoid regions that exclude the central portion of the second region in the widthwise direction of the base substrate; and

wherein the regions avoided by the high-bending-resistance portion relatively form the low-bending-resistance portions.

Sub
C2
B2

6. (Amended) The flexible interconnect substrate as defined in claim 1,

wherein the low-bending-resistance portions are formed in a straight line within the second region, across the width of the base substrate.